



# 30V N-CHANNEL ENHANCEMENT MODE MOSFET PowerDI3333-8

### **Product Summary**

BVDSS	R <sub>DS(ON)</sub> Max	I <sub>D</sub> Max Tc = +25°C
	11mΩ @ Vgs = 10V	58
30V	15.2mΩ @ V <sub>GS</sub> = 4.5V	49

### **Description and Applications**

This MOSFET is designed to minimize the on-state resistance (RDS(ON)) yet maintain superior switching performance, making it ideal for high-efficiency power-management applications.

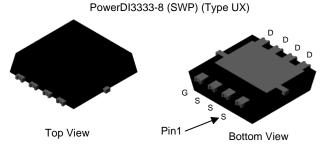
- Backlighting
- Power-Management Functions
- DC-DC converters

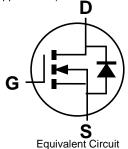
#### **Features and Benefits**

- Low Rds(ON) ensures on-state losses are minimized
- Small form factor thermally efficient package enables higher density end products
- Occupies just 33% of the board area occupied by SO-8 enabling smaller end product
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- For automotive applications requiring specific change control (i.e. parts qualified to AEC-Q100/101/104/200, PPAP capable, and manufactured in IATF 16949 certified facilities), please contact us or your local Diodes representative.
   https://www.diodes.com/quality/product-definitions/

### **Mechanical Data**

- Package: PowerDI<sup>®</sup>3333-8 (SWP) (Type UX)
- Package Material: Molded Plastic, "Green" Molding Compound.
   UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections Indicator: See Diagram
- Terminals: Finish Matte Tin Annealed over Copper Leadframe.
   Solderable per MIL-STD-202, Method 208<sup>(3)</sup>
- Weight: 0.072 grams (Approximate)





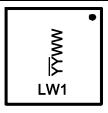
#### Ordering Information (Note 4)

Part Number	Package	Packing		
Fart Number	Fackage	Qty.	Carrier	
DMN3011LFVW-7	PowerDI3333-8 (SWP) (Type UX)	2,000	Tape & Reel	
DMN3011LFVW-13	PowerDI3333-8 (SWP) (Type UX)	3,000	Tape & Reel	

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- $4. For packaging details, go to our website at \ https://www.diodes.com/design/support/packaging/diodes-packaging/.$

## Marking Information



LW1 = Product Type Marking Code

YYWW = Date Code Marking

YY = Last Two Digits of Year (ex: 23 = 2023)

WW = Week Code (01 to 53)



### **Maximum Ratings** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit	
Drain-Source Voltage	VDSS	30	V	
Gate-Source Voltage	Vgss	±20	V	
Continuous Drain Current (Note 7) $V_{GS} = 10V$ $T_{C} = +25^{\circ}C$ $T_{C} = +70^{\circ}C$		lo	58 46	А
Pulsed Drain Current (10µs Pulse, Duty Cycle = 1%)	I <sub>DM</sub>	219	Α	
Maximum Continuous Body Diode Forward Current (Note 7)	Is	2.6	Α	
Pulsed Body Diode Forward Current (10µs Pulse, Duty Cycle = 1%)	Ism	219	Α	
Avalanche Current, L = 0.1mH (Note 8)		I <sub>AS</sub>	26	Α
Avalanche Energy, L = 0.1mH (Note 8)	Eas	34	mJ	

### Thermal Characteristics (@TA = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit	
Total Power Dissipation (Note 5)		PD	1.3	W
Thermal Resistance, Junction to Ambient (Note 5)	Steady State	$R_{\theta JA}$	94	°C/W
Total Power Dissipation (Note 6)		PD	2.6	W
Thermal Resistance, Junction to Ambient (Note 6)  Steady State		RθJA	48	°C/W
Thermal Resistance, Junction to Case (Note 7)		R <sub>θ</sub> JC	2.25	C/VV
Operating and Storage Temperature Range		T <sub>J</sub> , T <sub>STG</sub>	-55 to +150	°C

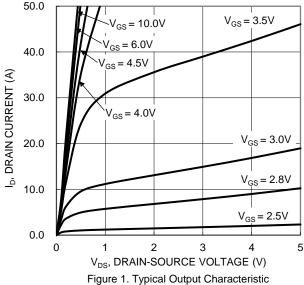
# **Electrical Characteristics** (@TA = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 9)							
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	30			V	$V_{GS} = 0V, I_{D} = 250\mu A$	
Zero Gate Voltage Drain Current	IDSS			1	μΑ	V <sub>DS</sub> = 30V, V <sub>GS</sub> = 0V	
Gate-Source Leakage	Igss	_	_	±100	nA	$V_{GS} = \pm 20V$ , $V_{DS} = 0V$	
ON CHARACTERISTICS (Note 9)							
Gate Threshold Voltage	V <sub>GS(TH)</sub>	1.4		2.25	V	$V_{DS} = V_{GS}$ , $I_D = 250\mu A$	
Static Drain-Source On-Resistance	D-s(s)		7	11	mΩ	VGS = 10V, ID = 30A	
Static Dialii-Source Ori-Resistance	RDS(ON)		10	15.2		V <sub>G</sub> S = 4.5V, I <sub>D</sub> = 15A	
Diode Forward Voltage	VsD	_	0.7	1.2	V	Vgs = 0V, Is = 1A	
DYNAMIC CHARACTERISTICS (Note 10)							
Input Capacitance	Ciss		1130	_	pF		
Output Capacitance	Coss		141		рF	V <sub>DS</sub> = 15V, V <sub>GS</sub> = 0V, f = 1MHz	
Reverse Transfer Capacitance	Crss		104	_	pF	] - 11V1F1Z	
Gate Resistance	Rg	_	2.49	_	Ω	$V_{DS} = 0V$ , $V_{GS} = 0V$ , $f = 1MHz$	
Total Gate Charge (VGS = 4.5V)	Qg		10	_	nC		
Total Gate Charge (V <sub>GS</sub> = 10V)	Qg	_	19.7	_	nC	\/ 45\/ I 40A	
Gate-Source Charge	Qgs	_	3.8	_	nC	V <sub>DS</sub> = 15V, I <sub>D</sub> = 12A	
Gate-Drain Charge	Q <sub>gd</sub>	_	1.4	_	nC	1	
Turn-On Delay Time	td(ON)		4.4	_	ns		
Turn-On Rise Time	t <sub>R</sub>	_	26.8	_	ns	V <sub>DD</sub> = 15V, V <sub>GS</sub> = 10V,	
Turn-Off Delay Time	tD(OFF)		27.1	_	ns	$R_L = 1.25\Omega$ , $R_G = 3\Omega$	
Turn-Off Fall Time	tF		20.8	_	ns		
Body Diode Reverse Recovery Time	t <sub>RR</sub>		9.2	_	ns	In - 124 di/dt - 5004/up	
Body Diode Reverse Recovery Charge	QRR	_	5.2	_	nC	I <sub>F</sub> = 12A, di/dt = 500A/μs	

Notes:

- 5. Device mounted on FR-4 PC board, with minimum recommended pad layout, single sided.6. Device mounted on FR-4 substrate PC board, 2oz copper, with thermal bias to bottom layer 1-inch square copper plate.7. Thermal resistance from junction to soldering point (on the exposed drain pad).
- 8.  $I_{AS}$  and  $E_{AS}$  ratings are based on low frequency and duty cycles to keep  $T_{J} = +25^{\circ}C$ .
- Short duration pulse test used to minimize self-heating effect.
   Guaranteed by design. Not subject to product testing.





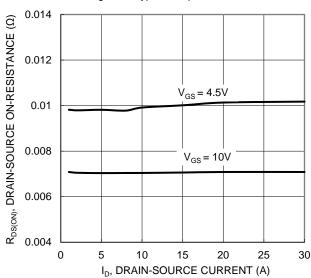


Figure 3. Typical On-Resistance vs. Drain Current and Gate Voltage

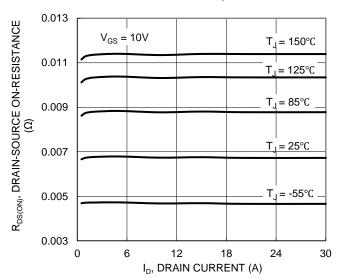


Figure 5. Typical On-Resistance vs. Drain Current and Temperature

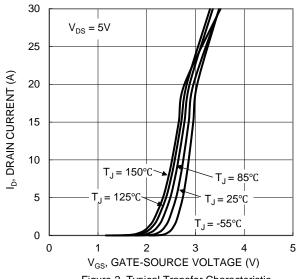
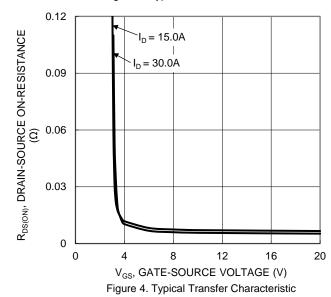


Figure 2. Typical Transfer Characteristic



1.8 R<sub>DS(ON)</sub>, DRAIN-SOURCE ON-RESISTANCE (NORMALIZED)  $V_{GS} = 10V, I_D = 30.0A$ 1.6 1.4 1.2  $V_{GS} = 4.5V, I_D = 15.0A$ 1 8.0 0.6 -50 25 50 75 100 125 T<sub>J</sub>, JUNCTION TEMPERATURE (°C)

Figure 6. On-Resistance Variation with Temperature



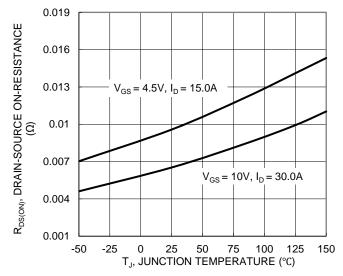
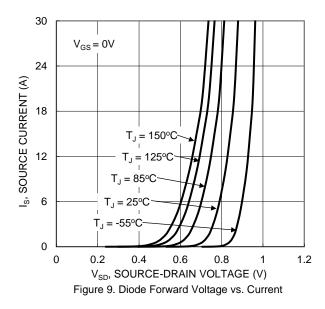


Figure 7. On-Resistance Variation with Temperature



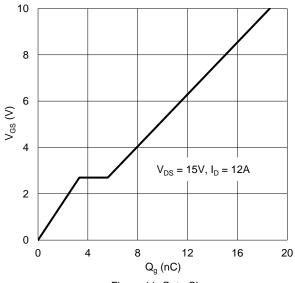


Figure 11. Gate Charge

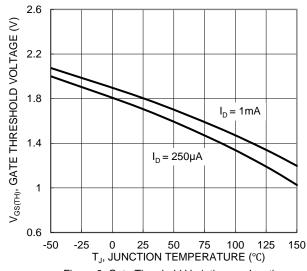
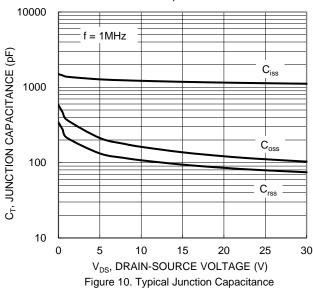


Figure 8. Gate Threshold Variation vs. Junction Temperature



1000 R<sub>DS(ON)</sub> Limited 100 ID, DRAIN CURRENT (A) 10 T<sub>J(Max)</sub> = 150°C = 100 msT<sub>C</sub> = 25°C Single Pulse **DUT** on Infinite Heatsink  $V_{GS} = 10V$ 0.1 0.1 10 100 V<sub>DS</sub>, DRAIN-SOURCE VOLTAGE (V) Figure 12. SOA, Safe Operation Area



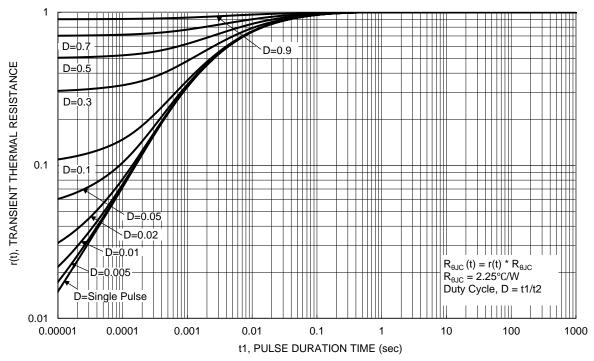


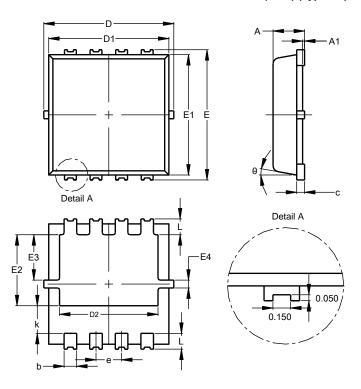
Figure 13. Transient Thermal Resistance



### **Package Outline Dimensions**

Please see http://www.diodes.com/package-outlines.html for the latest version.

### PowerDI3333-8 (SWP) (Type UX)

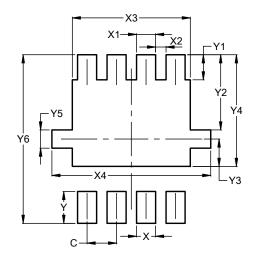


PowerDI3333-8 (SWP)						
(Type UX)						
Dim	Min	Max	Тур			
Α	0.75	0.85	0.80			
A1	0.00	0.05				
b	0.25	0.40	0.32			
С	0.10	0.25	0.15			
D	3.20	3.40	3.30			
D1	2.95	3.15	3.05			
D2	2.30	2.70	2.50			
Е	3.20	3.40	3.30			
E1	2.95	3.15	3.05			
E2	1.60	2.00	1.80			
E3	0.95	1.35	1.15			
E4	0.10	0.30	0.20			
е	_	_	0.65			
k	0.50	0.90	0.70			
L	0.30	0.50	0.40			
θ	0°	12°	10°			
All Dimensions in mm						

# **Suggested Pad Layout**

Please see http://www.diodes.com/package-outlines.html for the latest version.

#### PowerDI3333-8 (SWP) (Type UX)



Dimensions	Value (in mm)			
C	0.650			
X	0.420			
X1	0.420			
X2	0.230			
Х3	2.600			
X4	3.500			
Υ	0.700			
Y1	0.550			
Y2	1.650			
Y3	0.600			
Y4	2.450			
Y5	0.400			
Y6	3.700			



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